

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	ELECTROLESS PLATING METHOD	
Application Type :	regular, utility	
Attorney Docket Number :	040170	
Correspondence address:		
Customer Number:	23850	
Priority Data:		
Doc.No: 2003-117828; Country -JP ; Date: 2003-04-23 us-priority-claimed		
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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